

S9S12DG25F0CPVE :Part Detail

[Product Summary Page](#)
[General Information](#)
[Package Information](#)
[Environmental and Compliance Information](#)
[Manufacturing Information](#)
[Ordering Information](#)
[Product/Process Change Notice \(PCN\)](#)
[Operating Characteristics](#)
[Reliability Data Lookup](#)

GENERAL INFORMATION

Part Number	S9S12DG25F0CPVE
Description	16-bit MCU, S12 core, 256KB Flash, 25MHz, -40/+85degC, Automotive Qualified, QFP 112
Product Line	G9FTDG5K
PTI	JCJD
Material Type	Tested Packaged Device
Life Cycle Description (code)	NOT RECOMMENDED(DECLINING)
Status	Not Recommended for New Design
Application/Qualification Tier	AUTO; >=10 YEARS APPLICATION LIFE

PACKAGE INFORMATION

Package Type and Termination Count	LQFP 112
Package Description and Mechanical Drawing	LQFP 112 20*20*1.4P0.65
Device Weight(g)	1.27830
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	20.000
Package Width (nominal)(mm)	20.000
Package Thickness (nominal)(mm)	1.000
Maximum Height Above Board(mm)	1.600
Tape & Reel	No

ENVIRONMENTAL AND COMPLIANCE INFORMATION

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report
RoHS Certificate of Analysis (CoA)	Download RoHS CoA Report

2nd Level Interconnect	e3
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

MANUFACTURING INFORMATION

Micron Size(μm)	.25
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ORDERING INFORMATION

Minimum Package Quantity (MPQ)	300
MPQ Container	BRICK
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	600
POQ Container	BOX
Leadtime (weeks)	18
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency	1 @ US each
Device Sample Availability	19 Dec 2005
Device Production Availability	19 Dec 2005
Order	

PRODUCT/PROCESS CHANGE NOTICE (PCN)

Number	Type	Title	Issue Date	Effectivity Date
16253	Product Change Notice	0.25um ATMC and TSMCFAB3/11 KLM QFP Copper Wire and Leadframe Flag Conversion Qualification	09 Jun 2014	09 Dec 2014
14393A	Update Notification	9S12D256, 9S12DX12, AND 9S12XD64 MANUFACTURING IN TSMC3 IN TAIWAN	05 Nov 2010	28 Feb 2011

14393	Product Change Notice	9S12D256, 9S12Dx12, and 9S12xD64 manufacturing in TSMC3 in Taiwan	22 Oct 2010 11 May 2011
12300	Product Change Notice	ADDITION OF WINSTEK PROBE SITE FOR ATMC	11 Sep 200604 Sep 2006

OPERATING CHARACTERISTICS

ADC	8-ch. 10-bit
ADC (bit)	10
ADC (ch)	8
Additional Features	COP Internal Voltage Regulator PLL
Ambient Operating Temperature (Min-Max) (°C)	-40 to 85
Bus Frequency (Max) (MHz)	25
CAN	2
Core Type	S12
EEPROM (KB)	4
GPIOs	91
I2C	1
Internal Flash (KB)	256
Internal RAM (KB)	12
PWM	8-ch. 8-bit
PWM (bit)	8
PWM (ch)	8
Sample Exception Availability	N
SCI	2
SPI	3
Timers	8-ch. 16 bit

Reliability Data Lookup

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